TWEPP 2013 - Topical Workshop on Electronics for Particle Physics

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3D Integration, from tool box to applications

Friday, 27 September 2013 09:00 (45 minutes)

After a tremendous technology modules development phase, 3D integration is now looking for the right use cases. Miniaturization and bandwidth needs are partially addressed by 2,5D heterogeneous interposers, but with limited impacts on competitiveness and cost. Disruptive 3DIC stacking is potentially offering unmatched performances and scalability in both niche and consumers markets but is facing difficult integration challenges in terms of signal integrity, thermal/mechanical managements and reliability. Specific applications oriented technological solutions are today required and will be reviewed in this talk. We will discuss how microelectronic for particle physics and imaging is about to become one of the main driver and recipient of 3D integration.

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